

ABSTRACT OF THE DISCLOSURE

A probe pin for testing electric characteristics of a semiconductor device comprises a silicon pin core (3, 23, 33), and a conductive film (4, 24, 34) covering the entire surface, including the bottom face, of the pin core. The bottom face of the probe pin is connected directly to an electrode (7, 37) positioned in or on a print wiring board. A number of probe pins can be connected to the associated electrodes at a high density, thereby forming a fine-pitch probe card having a superior high-frequency signal characteristic.

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